OCP Leadership & Partners by the Numbers: A September 2026 Snapshot

Who leads the work, where they come from, and which organizations OCP partners with: the people and alliance figures behind the Community, updated monthly.

Open Compute Project Foundation · September 22, 2026

OCP by the Numbers tracks what the Community produces. This companion looks at who produces it: the volunteers who lead Projects, Sub-Projects and Workstreams, the Foundation staff who support them, and the industry organizations that have signed formal alliance agreements with OCP. Everything here is counted from the Foundation's own directories.

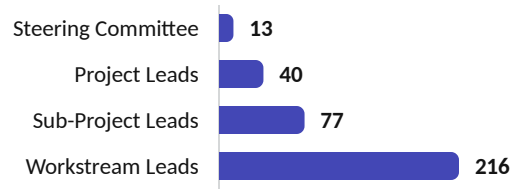
AT A GLANCE

281	130	25	26
Volunteer leaders	Companies represented	Foundation staff	Alliance partners
Baseline month	Baseline month	Baseline month	Baseline month

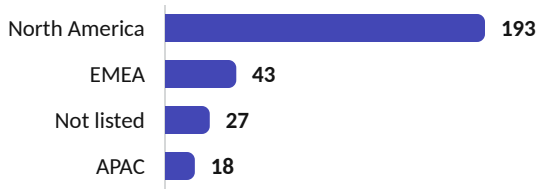
This is the baseline edition of the leadership and partners companion to OCP by the Numbers. From next month, each headline figure carries its change versus the prior month and a short 'What changed' section lists the largest movements.

Project leadership: 281 volunteers from 130 companies

OCP's engineering work is led by volunteers from member companies. The directory currently lists **346 leadership roles**: 13 Steering Committee seats, 40 Project Leads, 77 Sub-Project Leads and 216 Workstream Leads. Because 58 people hold more than one of those roles, they are filled by **281 individuals** drawn from 130 different companies.

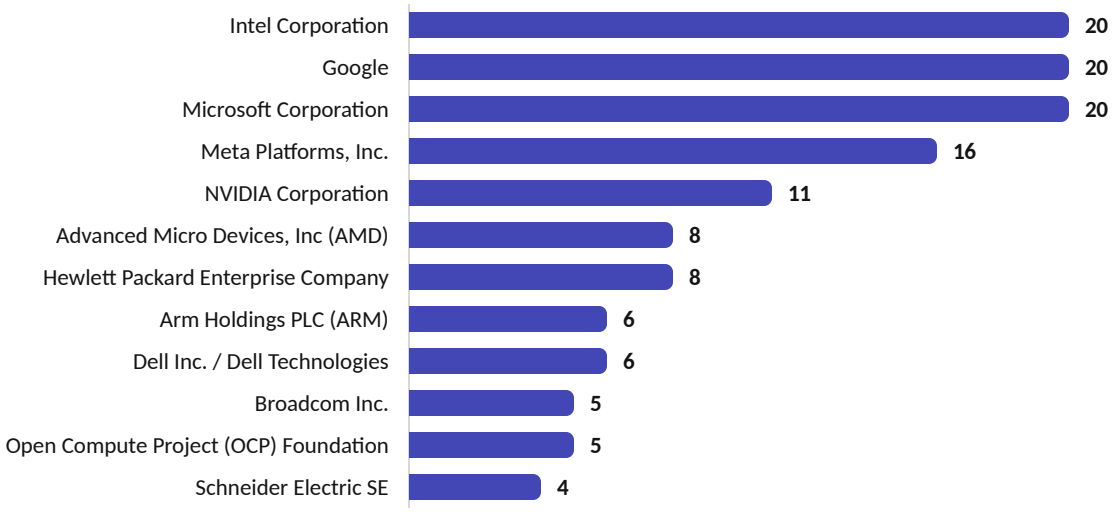


Leadership roles by tier. Roles, not people; one person can hold several.



Volunteer leaders by the region of their company's headquarters.

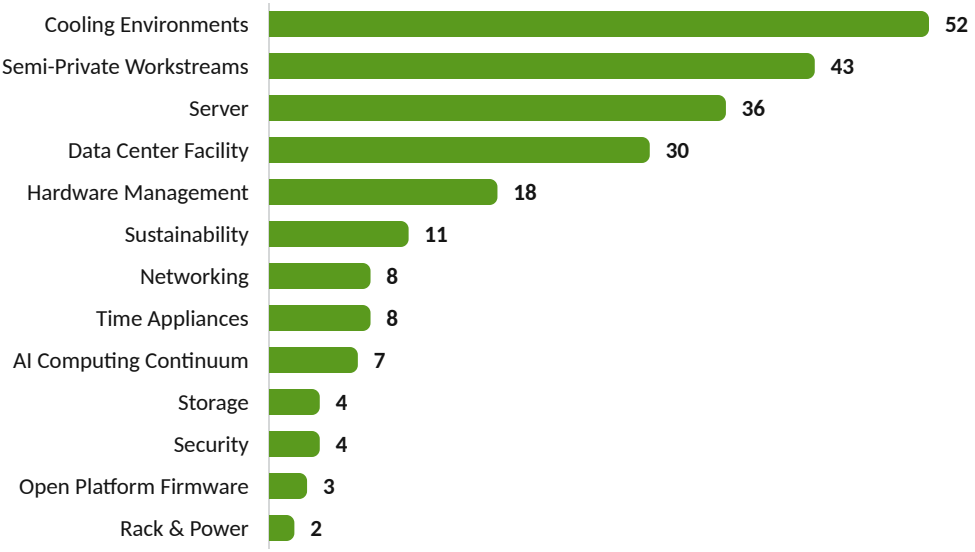
The bench is deep but concentrated. Intel Corporation, Google and Microsoft Corporation each field 20 leaders, and together the top three account for roughly 21 percent of all volunteer leaders; Meta Platforms, Inc. (16) and NVIDIA Corporation (11) follow. The Steering Committee's 13 members come from 9 companies, all Platinum members. Geographically, about 69 percent of leaders work for North American companies, with EMEA (43) and APAC (18) supplying most of the rest.



Companies with the most volunteer leaders (all lead roles combined). The Foundation's own staff hold 5 lead roles.

Where the leaders are: Cooling Environments has the largest bench

Counting every person who leads something under each Project, **Cooling Environments** has the most volunteer leaders at 52, drawn from 38 companies, followed by Semi-Private Workstreams (43) and Server (36). The member-only Semi-Private Workstreams program has 43 leaders from 18 companies. Beyond the Projects, the Strategic, Future Technologies and Incubation initiatives are led by a further 17 people, and the regional Community Groups by 21.



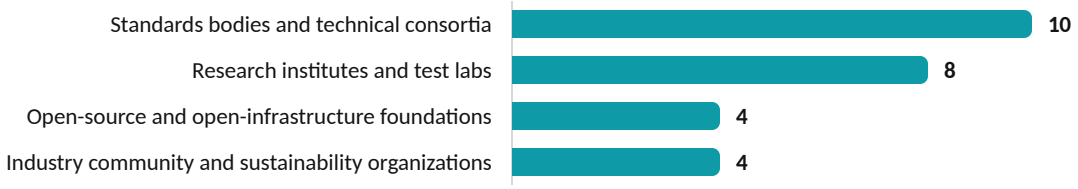
Volunteer leaders by Project (Steering Committee, Project, Sub-Project and Workstream leads combined; a person active in two Projects is counted in both). Company counts per Project are in the appendix.

Foundation staff: 25 people supporting the Community

The Foundation itself is small. **25 staff** run the Foundation's membership, events, marketing, finance and technical programs, and maintain the directories this report is drawn from. 5 of them also hold project leadership roles alongside their staff duties. That ratio, roughly one staff member for every 11 volunteer leaders and every 24 corporate members, is the leverage that open collaboration provides.

Alliance Partners: 26 organizations with formal agreements

OCP bridges to other communities through formal alliance agreements. **26 organizations** currently hold one, all active. 10 of them are standards bodies and technical consortia such as JEDEC, PCI-SIG, SNIA and the newer Ultra Ethernet and UALink consortia, which keeps OCP's specifications aligned with the interfaces the industry standardizes elsewhere. 8 are research institutes and test labs, 4 are open-source and open-infrastructure foundations, and 4 are industry community and sustainability organizations. The full list is in the appendix.



Alliance partners by kind of organization. The grouping is editorial; the site lists partners alphabetically.

Appendix: Alliance partners, leaders by Project, and roles by tier

Counts below are as shown in the Foundation's directories on the date of this post. Alliance partners are listed by name; the people behind each role are listed in the rosters that follow.

Alliance Partners: 26 organizations with formal agreements, grouped by kind of organization (the grouping is editorial; the site lists partners alphabetically).

- Standards bodies and technical consortia, 10: ASHRAE; Distributed Management Task Force (DMTF); ECMA; IOWN Global Forum; JEDEC; Open Standards for Digital Infrastructure (OIX); PCI-SIG; SNIA; Ultra Accelerator Link Consortium (UALink); Ultra Ethernet Consortium (UEC).
- Open-source and open-infrastructure foundations, 4: Open Infra Foundation; OpenUK; Stichting Current OS; The Linux Foundation.
- Research institutes and test labs, 8: IDA; Lawrence Berkeley National Laboratory (LBNL); National Institute of Information and Communications Technology (NICT); Numana; Research Institutes of Sweden (RISE); Southwest Research Institute (SwRI); University of New Hampshire InterOperability Lab; i14y Lab.
- Industry community and sustainability organizations, 4: Infrastructure Masons (iMasons); Net Zero Innovation Hub; Nomad Futurist Foundation; Sustainable Digital Infrastructure Alliance (SDIA).

Volunteer leaders by Project: unique people holding a Steering Committee, Project Lead, Sub-Project Lead or Workstream Lead role anywhere under the Project, and the number of companies they come from. A person active in two Projects is counted in both.

- Cooling Environments: 52 leaders from 38 companies.
- Semi-Private Workstreams: 43 leaders from 18 companies.
- Server: 36 leaders from 27 companies.
- Data Center Facility: 30 leaders from 22 companies.
- Community Groups: 21 leaders from 17 companies.
- Hardware Management: 18 leaders from 8 companies.
- Sustainability: 11 leaders from 10 companies.
- Future Technologies Initiative: 11 leaders from 10 companies.
- Time Appliances: 8 leaders from 7 companies.
- Networking: 8 leaders from 8 companies.
- AI Computing Continuum: 7 leaders from 5 companies.
- Storage: 4 leaders from 4 companies.
- Security: 4 leaders from 2 companies.
- Open Platform Firmware: 3 leaders from 3 companies.
- Incubation Initiatives: 3 leaders from 3 companies.
- Strategic Initiatives: 3 leaders from 3 companies.
- Rack & Power: 2 leaders from 2 companies.

Leadership roles by tier: people and companies per role, and where those companies are headquartered.

- Steering Committee: 13 people from 9 companies (North America 7; APAC 1; EMEA 1).
- Project Leads: 40 people from 26 companies (North America 18; EMEA 4; Not listed 3; APAC 1).
- Sub-Project Leads: 77 people from 46 companies (North America 22; EMEA 14; APAC 7; Not listed 3).
- Workstream Leads: 216 people from 107 companies (North America 58; Not listed 22; EMEA 19; APAC 7).

Appendix: Rosters

Who holds each role, as listed in the Foundation directory. Contact details are not included.

Steering Committee (13), name and company.

Mike Allison, Samsung Electronics Co.; Harsha Bojja, Google; Madhusudan Iyengar, Google; Andres Lagar-Cavilla, Google; John Leung, Intel Corporation; Steve Mills, Meta Platforms, Inc.; Roksana Golizadeh Mojarad, Microsoft Corporation; Gregory D Sellman, Advanced Micro Devices, Inc (AMD); Shruti Sethi, Microsoft Corporation; Sean Varley, Ampere Computing; Xu Wang, Meta Platforms, Inc.; Dong Wei, Arm Holdings PLC (ARM); Elad Wind, NVIDIA Corporation.

Foundation staff (25), name and title.

Raul Alvarez, European Market Development Manager; Zane Ball, Chief Technology Officer; Steven Bates, Chief Information Officer; Allie Bodnar, Marketing & Events Manager; Nick Bullock, Chief Financial Officer; Kali Burdette, Senior Director of Global Events; Bill Carter, Fellow Emeritus; Rob Coyle, Sr. Director of Member Experience; Mark Dansie, Head of Data Center Facility Programs; Eric Fritsch, Controller; Steve Helvie, Chief Emerging Ecosystem Officer; Kate Hendle, Manager of Events; Laura Holst, Operations Coordinator; Andrew Jones, Member Experience Specialist; James Kelly, VP Market Intelligence and Innovation; Kevin Kifer, Director of IT & Digital Services; Ewa McCurdy, SP Program Manager; Vy Nguyen, SP Program Coordinator; Cliff Grossner Ph.D., Chief Innovation Officer; Jonae Powers, Event Coordinator; Alicia Schap, Community Operations Specialist; Michael Schill, Sr Director of Community; Dirk Van Slyke, Chief Marketing Officer; George Tchaparian, CEO; Russ Wunderlich, Principal HW Engineer.

Project Leads (40), grouped by Project, name and company.

Community Groups (4): Allison Griffis Boen, Alcatex Incorporated; Sung A Kim, BP / Castrol Lmtd / Lubricants UK Limited; Anu Ramamurthy, Microchip Technology, Inc.; Shruti Sethi, Microsoft Corporation.

Cooling Environments (4): Allison Griffis Boen, Alcatex Incorporated; John Edward Fernandes, Meta Platforms, Inc.; Sean Sivapalan, NVIDIA Corporation; Harry Soin, Advanced Energy Industries, Inc. (AEI) / Artesyn.

Data Center Facility (3): Saket Karajgikar, NVIDIA Corporation; Vivek Prasad, Microsoft Corporation; Scott Sharp, Google.

Open Platform Firmware (3): Raj Kapoor, Advanced Micro Devices, Inc (AMD); Murugasamy Nachimuthu, Oracle Corporation; Jean-Marie Verdun, Hewlett Packard Enterprise Company.

Semi-Private Workstreams (3): Bryan Kelly, Microsoft Corporation; Lee Prewitt, Microsoft Corporation; Ross Stenfort, Sandisk Technologies Inc..

Server (3): Jeff Kennedy, Dell Inc. / Dell Technologies; Anu Ramamurthy, Microchip Technology, Inc.; John Stuewe, Strategic Thermal Labs LLC.

Sustainability (3): Rishab Vardhan Vardhan Harikrishnan, Oracle Corporation; Sung A Kim, BP / Castrol Lmtd / Lubricants UK Limited; Alexander Rakow, Schneider Electric SE.

AI Computing Continuum (2): Dirk Blevins, Intel Corporation; Vincent Nguyen, Hewlett Packard Enterprise Company.

Future Technologies Symposium (2): Poh Seng Lee Ph.D., National University of Singapore; Jon Summers Ph.D., RISE Research Institute.

Hardware Management (2): Jeff Hilland, Hewlett Packard Enterprise Company; Hemal Shah, Broadcom Inc..

Networking (2): Barak Gafni, NVIDIA Corporation; Ravindra Sunkad, Meta Platforms, Inc..

Rack & Power (2): Steven Moore, Rittal GmbH & Co. KG; Harry Soin, Advanced Energy Industries, Inc. (AEI) / Artesyn.

Security (2): Jeff Andersen, Google; Bryan Kelly, Microsoft Corporation.

Storage (2): Lee Prewitt, Microsoft Corporation; Ross Stenfort, Sandisk Technologies Inc..

Future Technologies Initiative (1): Boniface Yogendran, Defence Research and Development Canada.

Strategic Initiatives (1): Loren Staley, Celestica International LP.

Time Appliances (1): Ahmad Byagowi, Turbalance, Inc..

No project link on the site (7): Jeff Hillard Autor, Hewlett Packard Enterprise Company; Eric Dahlen, Intel Corporation; Dean Gladish, Daedaelus Corporation; Zahra Lak; Maheshwari Neelam, USRA; Karl Rabe, Wooden Data Center; Vladislav Sahnovich, Google.

Sub-Project Leads (77), grouped by Project, name and company.

Community Groups (15): Raul Alvarez; jeroen burks, Blockheating; Alex Chou, Submer Inc.; HsingChou Hsu, Intel Corporation; Kelvin Huang, Microsoft Corporation; Sung A Kim, BP / Castrol Lmtd / Lubricants UK Limited; Michael Kim, Samsung Electronics Co.; Jungsoo Kim, FADU Inc.; Taehoon Lee, SK Hynix America Inc.; Wai Chung Ngai, Advanced Micro Devices, Inc (AMD); Anu Ramamurthy, Microchip Technology, Inc.; Shruti Sethi, Microsoft Corporation; Nill Shijian Ge Shijian, Beijing ByteDance Network Technology Co., Ltd; Kaoru Yamaguchi, RSI; Peter Ye Ye, Inspur Electronic Information Industry Co. (IEIT Systems).

Cooling Environments (14): Rolf Brink, Promersion; Brian Burbank, Vertiv Holdings Co; Emily Clark, Dell Inc. / Dell Technologies; Jaime Comella, DayOne Data Centers Limited; Martin Doerrich, Rittal GmbH & Co. KG; Jabari George, J.M. Gross Engineering, LLC; Jessica Gullbrand, Eaton Corporation; Michael Jones, Vertiv Holdings Co; Hussameddine Kabbani, Google; Matt Koukl, Advanced Energy Industries, Inc. (AEI) / Artesyn; John Menoche, Vertiv Holdings Co; Bharath Ramakrishnan, Microsoft Corporation; Pardeep Shahi, NVIDIA Corporation; Berhanu Wondimu, Intel Corporation.

Server (13): Brian Aspnes, Intel Corporation; Allan Cantle, Nallasway, Inc.; Damien Chong, Meta Platforms, Inc.; Shawn Dube, Dell Inc. / Dell Technologies; Mohamad El-Batal, Seagate Technology LLC; Majid Foodeei, TeraSignal; Mark Knight, Arm Holdings PLC (ARM); Robert Lo, Industrial Technology Research Institute (ITRI); Jawad Nasrullah, Palo Alto Electron, Inc.; Samir Rajadnya, Microsoft Corporation; Anu Ramamurthy, Microchip Technology, Inc.; Manoj Wadekar, Meta Platforms, Inc.; Kasper Wszolek, NVIDIA Corporation.

Data Center Facility (10): Vijay Boovaragavan, Google; Joshua Buzzel, Bitdeer; Paolo Catapane, ABB Integrated DC Power; Priya Chhiba, Google; Shashank Gupta, Fleet Data Centers; Sean James, NVIDIA Corporation; Avinash Panga, Google; Daniel Robbins, RakworX; Scott Sharp, Google; Eric Xu, Meta Platforms, Inc..

Semi-Private Workstreams (8): Brian Aspnes, Intel Corporation; Shawn Dube, Dell Inc. / Dell Technologies; Utkarsh Kakaiya, Intel Corporation; Bharath Parthasarathy, Google; Lee Prewitt, Microsoft Corporation; Ross Stenfort, Sandisk Technologies Inc.; Manoj Wadekar, Meta Platforms, Inc.; Kasper Wszolek, NVIDIA Corporation.

Hardware Management (4): Brian Vandecoevering, Hewlett Packard Enterprise Company; Drew Walton, Microsoft Corporation; Han Wang, Meta Platforms, Inc.; Zhengyu Yang, Meta Platforms, Inc..

Networking (4): Michael DeMerchant, Lumentum; Rita Hui, Microsoft Corporation; Iwan Kartawira, iPronics; Steven Noble, Network Device Education Foundation.

AI Computing Continuum (3): Thomas Nadeau, Lucid Vision; Azhar Sayeed, NG Voice; Bradford Stimpson, Bell Mobility.

Security (2): Eric Eilertson, Microsoft Corporation; Nick Hummel, Google.

Storage (2): Lee Prewitt, Microsoft Corporation; Ross Stenfort, Sandisk Technologies Inc..

Sustainability (2): Sung A Kim, BP / Castrol Lmtd / Lubricants UK Limited; Alexander Rakow, Schneider Electric SE.

Incubation Initiatives (1): Adrian Enache, Meta Platforms, Inc..

Open Platform Firmware (1): Jean-Marie Verdun, Hewlett Packard Enterprise Company.

Time Appliances (1): Georgi Chalakov, NVIDIA Corporation.

No project link on the site (5): Ann-Kathrin Dechert, Rittal GmbH & Co. KG; Jack Harwood, Dell Inc. / Dell Technologies; Jordan Johnson, Intel Corporation; John Kaczala, NOKIA Corporation; Karl Rabe, Wooden Data Center.

Workstream Leads (216), grouped by Project, name and company.

Cooling Environments (46): Tina Bao, TE Connectivity plc; John Bean, Green Revolution Cooling, Inc; Nicholas Beardsley, Green Revolution Cooling, Inc; Steven Bischof, Chevron Phillips Chemical; Allison Griffis Boen, Alcatex Incorporated; Harsha Bojja, Google; Vanja Boyd, ExxonMobil(Malaysia); Rolf Brink, Promersion; JANELSA CARTY, Shell Global Solutions; Oriol Chavanel, Submer Technologies, S.L.; Cheng Chen, Meta Platforms, Inc.; Emily Clark, Dell Inc. / Dell Technologies; Peter Cooper, Promersion; John Edward Fernandes, Meta Platforms, Inc.; Kris Fletcher, BP / Castrol Lmtd / Lubricants UK Limited; David Gardiner, Gardiner and Associates; Jabari George, J.M. Gross Engineering, LLC; Bobby Glidwell, Magnalytix LLC; Jessica Gullbrand, Eaton Corporation; Austin Hipes, UNICOM Engineering, Inc.; Hussameddine Kabbani, Google; Rajesh Kasukurthy, Meta Platforms, Inc.; Spencer Kerns, Chevron Philips Chemical; Jack Kolar, Frontinus Innovations LLC; Matt Koukl, Advanced Energy Industries, Inc. (AEI) / Artesyn; Gabriel Lazar Lazar, Submer Technologies, S.L.; Peter Liu, Formerica Optoelectronics Inc.; Alex Mcmanis, ENEOS USA Inc.; John Menoche, Vertiv Holdings Co; Maryam Mohagheghi, HF Sinclair; Khaled Morsy, Bureau Veritas Mission Critical; Cosimo Pecchioli Pecchioli, Individual; Alex Pica, Saint-Gobain Performance Plastics Corporation; Gemma Reeves, Alfa Laval Group; Eduard Roytman, Microsoft Corporation; Florian Rüping, BP / Castrol Lmtd / Lubricants UK Limited; Pardeep Shahi, NVIDIA Corporation;

Amy Short, Denvr Dataworks; David Sickinger, National Renewable Energy Laboratory; Harry Soin, Advanced Energy Industries, Inc. (AEI) / Artesyn; Petter Terenius, Uppsala University; Romà Surís Valls, Submer Technologies, S.L.; Berhanu Wondimu, Intel Corporation; Samantha Yates, Intel Corporation; Andy E Young, Asperitas; Bradley Zakaib, CoolIT Systems.

Semi-Private Workstreams (42): Mike Allison, Samsung Electronics Co.; Brian Aspnes, Intel Corporation; Michelle Badal, Google; Chinnakrishnan Ballapuram, Sandisk Technologies Inc.; Stephan Benecke, Google; Abhik Bera, Schneider Electric SE; Mark Dansie; Eric Davis, Broadcom Inc.; Clifford H DuBay, Intel Corporation; Shawn Dube, Dell Inc. / Dell Technologies; Chris Eckstein, Fraunhofer IOSB; Tom Emmons, Arista Networks Solutions, Inc; Corey Hartman, Dell Inc. / Dell Technologies; David Heinrich, Hewlett Packard Enterprise Company; Steve Helvie; Amber Huffman, Google; Madhusudan Iyengar, Google; Mike James, Sandisk Technologies Inc.; Janusz Jurski, Intel Corporation; Bryan Kelly, Microsoft Corporation; Kyungtaek Kim, Solidigm; Santosh Kumar, Solidigm; Lowell Lamb, Broadcom Inc.; Dave Landsman, Western Digital Corporation (WDC); Phillip Leech, Hewlett Packard Enterprise Company; Pratik Marolia, Microsoft Corporation; Kevin Mundt, Advanced Micro Devices, Inc (AMD); Bharath Parthasarathy, Google; Bharat Pillilli, Microsoft Corporation; Lee Prewitt, Microsoft Corporation; Lisa Rivalin, Meta Platforms, Inc.; Kially M. Ruiz, Cibao Cloud Technologies; Bill Scherer, Hewlett Packard Enterprise Company; Karsten Schischke, Fraunhofer IOSB; Gregory D Sellman, Advanced Micro Devices, Inc (AMD); Rip Sohan, Advanced Micro Devices, Inc (AMD); Ines Sousa, Microsoft Corporation; Eric Spada, Broadcom Inc.; Ross Stenfort, Sandisk Technologies Inc.; Manoj Wadekar, Meta Platforms, Inc.; Qian Wang, NVIDIA Corporation; Kasper Wszolek, NVIDIA Corporation.

Server (30): Elad Alon, Blue Cheetah Analog; Brian Aspnes, Intel Corporation; Mike Bartley, Tessolve Semiconductors Pvt. Ltd.; Dominic Brown, Arm Holdings PLC (ARM); Allan Cantle, Nallasway, Inc.; Anjaneya “Reddy” Chagam, Intel Corporation; Shawn Dube, Dell Inc. / Dell Technologies; Mohamad El-Batal, Seagate Technology LLC; Samer El-Haj-Mahmoud, Arm Holdings PLC (ARM); Rohit Gupta, Applied Materials, Inc.; Mark Knight, Arm Holdings PLC (ARM); Timothy Lambert, Dell Inc. / Dell Technologies; Javier Lasa, Intel Corporation; Pankaj Mehra, Elephance Memory; Brian Murray, VeriSilicon Microelectronics (Shanghai) Co., Ltd.; Itai Nadler, GSOC Solutions; Jawad Nasrullah, Palo Alto Electron, Inc.; Robert Pelt, Advanced Micro Devices, Inc (AMD); Rajesh Pendurkar, Cadence Design Systems Inc.; Weifeng Zhang Ph.D., Lenovo Group Limited; Lin Kuang Kuo PhD, Applied Materials, Inc.; Anu Ramamurthy, Microchip Technology, Inc.; David Ratchkov, Thrace Systems; Vishal Shah, Credo Technology Group Holding Ltd.; Raghu Shankar, Self Employed; Manoj Wadekar, Meta Platforms, Inc.; Bow Wang, Quanta Cloud Technology (QCT); Dong Wei, Arm Holdings PLC (ARM); Morgan Whately, Infineon Technologies Ag; Kasper Wszolek, NVIDIA Corporation.

Data Center Facility (24): Maria Abadie, Google; Antonello Antoniazzi, ABB S.p.A.; Joshua Buzzel, Bitdeer; Paolo Catapane, ABB Integrated DC Power; Mark Dansie; Brian Deckard, Siemens AG; Aurelio Rodriguez Echevarria, Advanced Micro Devices, Inc (AMD); Lisa Grams, UL Solutions Inc.; Ben Gully, SPOC Energy; Shashank Gupta, Fleet Data Centers; Dan Lambert, ZincFive, Inc.; Tony Landry, Schneider Electric SE; Laurens Mackay, DC Opportunities; Don Mitchell, Victaulic Company; Hayley Moore, Google; Vivek Prasad, Microsoft Corporation; Scott Sharp, Google; Disha Sheth, Google; Shrikanth Venkateshappa, Flex Ltd.; Rudy Wang, Delta Electronics, Inc; Jing Wang, Google; Aaron Wemhoff, Villanova University; Eric Xu, Meta Platforms, Inc.; Sheng Zhong, ABB (Asea Brown Boveri Ltd.).

Hardware Management (15): Marko Bartscherer, Intel Corporation; Enrico Carrieri, QUALCOMM Incorporated; Samer El-Haj-Mahmoud, Arm Holdings PLC (ARM); Jim Harford, Broadcom Inc.; Jeff Hilland, Hewlett Packard Enterprise Company; Janusz Jurski, Intel Corporation; John Leung, Intel Corporation; Jose Marinho, Arm Holdings PLC (ARM); Bharat Pillilli, Microsoft Corporation; Hari Ramachandran, Microsoft Corporation; Hemal Shah, Broadcom Inc.; Yogesh Varma, Intel Corporation; Drew Walton, Microsoft Corporation; Dong Wei, Arm Holdings PLC (ARM); Theo Yigzaw, NVIDIA Corporation.

Future Technologies Initiative (11): Peter Abrell, Vision Electric Superconductors; Jonathan Burnett, UK Research and Innovation; JonMichael Hands, FarmGPU; Bobby Lu, Lightelligence PTE LTD; Yann-Guirec Manac'h, SCALEWAY SAS; Bill Martin, Samsung Electronics Co.; Kyle McCrindle, Denvr Dataworks; Jason Molgaard, Solidigm; Ron Swartzentruber, Lightelligence PTE LTD; Shrikanth Venkateshappa, Flex Ltd.; Boniface Yogendran, Defence Research and Development Canada.

Sustainability (11): Michael Anderson, SPX Cooling Tech; Daniel Cartagena, Intel Corporation; Ryan Cornwell, Google; Andrea Desimone, Schneider Electric SE; Miranda Gardiner, Climate Accord; Rishab Vardhan Vardhan Harikrishnan, Oracle Corporation; Howard Hsu, Meta Platforms, Inc.; Griff Keller, Vertiv Holdings Co; Sung A Kim, BP / Castrol Lmtd / Lubricants UK Limited; Maheshwari Neelam, NASA; Alexander Rakow, Schneider Electric SE.

Community Groups (10): Raul Alvarez; Allison Griffis Boen, Alcatex Incorporated; GuangYao Cao, Lenovo Group Limited; Terry Gong, Beijing ByteDance Network Technology Co., Ltd; HsingChou Hsu, Intel Corporation; Sung A Kim, BP / Castrol Lmtd / Lubricants UK Limited; Keno Li, Maginfra; Shuo Liu, Intel Corporation; Anu Ramamurthy, Microchip Technology, Inc.; Spike Yuan, Advanced Micro Devices, Inc (AMD).

Time Appliances (7): Paul Borrill, Daedaelus Corporation; Ahmad Byagowi, Turbalance, Inc.; Hesham Elbakoury, Innovax Technologies; David Johnston, Primitive Security; Sahas Munamala, Daedaelus Corporation; Wil Myrick, ENSCO, Inc.; Ankur Sharma, Equinix.

AI Computing Continuum (4): Brian Baker, Intel Corporation; Dirk Blevins, Intel Corporation; David Heinrich, Hewlett Packard Enterprise Company; Vincent Nguyen, Hewlett Packard Enterprise Company.

Networking (4): Chris Collins, Credo Technology Group Holding Ltd.; Stephen Manley, Oracle Corporation; Steven Noble, Network Device Education Foundation; Ravindra Sunkad, Meta Platforms, Inc..

Storage (4): Mike Allison, Samsung Electronics Co.; Amber Huffman, Google; Lee Prewitt, Microsoft Corporation; Ross Stenfort, Sandisk Technologies Inc..

Security (3): Eric Eilertson, Microsoft Corporation; Nick Hummel, Google; Bryan Kelly, Microsoft Corporation.

Strategic Initiatives (3): Rob Coyle; Lowell Lamb, Broadcom Inc.; Loren Staley, Celestica International LP.

Incubation Initiatives (2): Stephen Clement, Interact DC; Matthew Kaufeler, Cadence Design Systems Inc..

Circularity (1): Ian Lovell, Refurb Holdings, LLC.

Rack & Power (1): Harry Soin, Advanced Energy Industries, Inc. (AEI) / Artesyn.

No project link on the site (19): Alex Akesson, Microsoft Corporation; Donald Barnetson, Credo Technology Group Holding Ltd.; rama bhimanadhuni, Microsoft Corporation; Enrico Carrieri, Intel Corporation; Glenn Charest, Meta Platforms, Inc.; shashank gupta, Microsoft Corporation; Rohit Gupta, Arm Holdings PLC (ARM); David Gyulnazaryan, Impleon; Jordan Johnson, Intel Corporation; Hussameddine Kabbani, Microsoft Corporation; YANG SEOK KI, Samsung Electronics Co.; Robert Lo, Graphcore Limited; Ewa McCurdy; Chris Petersen, Meta Platforms, Inc.; Punith Shivaprasad, Shell Global Solutions; Michael Shych, NVIDIA Corporation; Durgesh Srivastava, DataraAI; JING WANG, Server Technology, Inc.; Qian Wang, Intel Corporation.

A person who leads in more than one Project is listed under each. Names and titles are as recorded in the Foundation directory.

Figures as of September 22, 2026. Region is the headquarters region recorded for a leader's company; 27 leaders' companies have no region recorded. Two leaders' companies are tagged 'Germany' rather than a region on the site; counted in EMEA.